

42390.P13267



PATENT

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#6/Response  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Sambasivam, et al.

Serial No.: 10/033,854

Filed: December 19, 2001

For: UNDERFILL MATERIALS  
DISPENSED IN A FLIP CHIP  
PACKAGE BY WAY OF A  
THROUGH HOLE

Examiner: Khiem Nguyen

Group Art Unit: 2823

Attorney Docket No.: 42390.P13267

CERTIFICATE OF MAILING

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RESPONSE AFTER FINAL REJECTION

Box AF  
Hon. Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Final Office Action mailed December 3, 2002, please consider  
the following remarks: